Fan, X. J., Zhou, J., Zhang, G. Q., and Ernst, L. J. — A Micromechanics-Based Vapor Pressure Model in Electronic Packages. **127,** 262–267
Felba, Jan — (see Mościcki, Andrzej) **127,** 91–95
Fiveland, Eric — (see Rubinsztajn, Slawomir) **127,** 77–85
Frear, D. — (see Basaran, C.) **127,** 157–163
Fujimoto, Kozo — (see Kim, Jong-Min) **127,** 18–24
_____ (see Yasuda, Kiyokazu) **127,** 12–17
Fushinobu, Kazuyoshi, and Nakata, Masashi — An Experimental and Numerical Study of a Liquid Mixing Device for Microsystems. **127,** 141–146

Garg, Jivtesh, Arik, Mehmet, Weaver, Stanton, Wetzel, Todd, and Saddoughi, Seyed — Meso Scale Pulsating Jets for Electronics Cooling. **127,** 503–511
Geers, M. G. D., Kouznetsova, V., and Brekelmans, W. A. M. — Multiscale Mechanics in Microelectronics: A Paradigm in Miniaturization. **127,** 255–261
Ghorbani, H. R., and Spelt, J. K. — Interfacial Thermal Stresses in Trilayer Assemblies. **127,** 314–323
Gillespie, John J., Jr. — (see Obaid, Ahmad Abu) **127,** 430–439
Gillespie, John W., Jr. — (see Obaid, Ahmad Abu) **127,** 483–495
Glezer, Ari — (see Mahalingam, Raghav) **127,** 172–177
Gomez, J. — (see Basaran, C.) **127,** 208–214
Gonda, V., den Toonder, J., Beijer, J., Zhang, G. Q., and Ernst, L. J. — Finite Thickness Influence on Spherical and Conical Indentation on Viscoelastic Thin Polymer Film. **127,** 33–37
_____ (see Jansen, K. M. B.) **127,** 530–536

Hadim, Hamid, and Suwa, Tohru — A Multidisciplinary Design and Optimization Methodology for Ball Grid Array Packages Using Artificial Neural Networks. **127,** 306–313
Ham, Suk-Jin — (see Kwon, Woon-Seong) **127,** 86–90
Hao, Lin — (see Yu, Xiaomei) **127,** 38–42
Hashmi, M. S. J. — (see Eveloy, Valérie) **127,** 245–254
_____ (see Rodgers, Peter) **127,** 67–75
Haswell, Peter — (see Zhang, Qian) **127,** 512–522
Hopkins, D. C. — (see Basaran, C.) **127,** 157–163
Horng, Jenn-Tsong — (see Chen, Han-Ting) **127,** 397–406
Hu, Mason — (see Ahmad, Mudasir) **127,** 290–298
Hubbard, Ken — (see Ahmad, Mudasir) **127,** 290–298
Hung, Tzu-Chen — (see Wang, S. Kong) **127,** 523–529
Hung, Ying-Huei — (see Chen, Han-Ting) **127,** 397–406
_____ (see Jeng, Tzer-Ming) **127,** 223–234
_____ (see Wu, Ming-Chang) **127,** 474–482
Hwang, Sheng-Jye — (see Pei, Chien-Chang) **127,** 324–334
_____ (see Pei, Chien-Chang) **127,** 335–339

Islam, M. N., Chan, Y. C., Alam, M. O., and Sharif, A. — Comparative Study of the Dissolution Kinetics of Electrolytic Ni and Electroless NiP Layers by Molten Sn3.5Ag Solder Alloy. **127,** 365–369
Islam, Rashed Adnan, and Chan, Y. C. — Behavior of Anisotropic Conductive Film (ACF) Joint under Mechanical Shock. **127,** 375–380

Jansen, K. M. B., Gonda, V., Ernst, L. J., Bressers, H. J. L., and Zhang, G. Q. — State-of-the-Art of Thermo-Mechanical Characterization of Thin Polymer Films. **127,** 530–536
Jen, Ming-Hwa R., Liu, Lee-Cheng, and Wu, Jenq-Dah — Flip-Chip Ball Grid Array Lead-Free Solder Joint Under Reliability Test. **127,** 446–451
Jeng, Tzer-Ming, Liu, Li-Kang, and Hung, Ying-Huei — A Novel Semi-empirical Model for Evaluating Thermal Performance of Porous Metallic Foam Heat Sinks. **127,** 223–234
Joshi, Yogendra — (see Rambo, Jeffrey) **127,** 452–459

Khan, Subhotosh — (see Obaid, Ahmad Abu) **127,** 430–439
_____ (see Obaid, Ahmad Abu) **127,** 483–495
Kim, Jang-Kyo — (see Sham, Man-Lung) **127,** 47–51
Kim, Jong-Min, Yasuda, Kiyokazu, and Fujimoto, Kozo — Resin Self-Alignment Processes for Self-Assembly Systems. **127,** 18–24
_____ (see Yasuda, Kiyokazu) **127,** 12–17
Kim, Jungho — (see Coursey, Johnathan S.) **127,** 127–134
Koch, M. — (see Becker, K.-F.) **127,** 1–6
Kouznetsova, V. — (see Geers, M. G. D.) **127,** 255–261
Kudzia, Józef — (see Mościcki, Andrzej) **127,** 91–95
Kundu, T. — (see Dube, M.) **127,** 147–156
Kuo, Sheng-Tzung — (see Wu, Ming-Chang) **127,** 474–482
Kwon, Woon-Seong, Yim, Myung-Jin, Paik, Kyung-Wook, Ham, Suk-Jin, and Lee, Soon-Bok — Thermal Cycling Reliability and Delamination of Anisotropic Conductive Adhesives Flip Chip on Organic Substrates With Emphasis on the Thermal Deformation. **127,** 86–90

Lai, Yi-Shao — (see Wang, Tong Hong) **127,** 135–140
Lai, Zonghe — (see Cao, Liqiang) **127,** 43–46
Lamontia, Mark A. — (see Obaid, Ahmad Abu) **127,** 430–439
_____ (see Obaid, Ahmad Abu) **127,** 483–495
Lau, John, and Dauksher, Walter — Reliability of an 1657CCGA (Ceramic Column Grid Array) Package With 95.5SN3.9AG0.6CU Lead-Free Solder Paste on PCBS (Printed Circuit Boards). **127,** 96–105
Lee, D. H. — (see Chung, Y. S.) **127,** 106–112(TB)
Lee, K. K., Tan, S. C., and Chan, Y. C. — Investigation of Conductive Adhesive Bonding Using UV Curable Anisotropic Conductive Adhesives at Different Curing Conditions. **127,** 52–58
Lee, Kang Yong — (see Yang, Ji Hyuck) **127,** 164–171
Lee, Soon-Bok — (see Kwon, Woon-Seong) **127,** 86–90
_____ (see Park, Tae-Sang) **127,** 237–244
Li, G. Y. — (see Chen, B. L.) **127,** 466–473
Li, Ting — (see Yu, Xiaomei) **127,** 38–42
Ligrani, P. M. — (see Chung, Y. S.) **127,** 106–112(TB)
Lim, S. C. — (see Zhong, Z. W.) **127,** 25–28
Lin, J. K. — (see Basaran, C.) **127,** 157–163
Liu, Johan — (see Cao, Liqiang) **127,** 43–46
Liu, Lee-Cheng — (see Jen, Ming-Hwa R.) **127,** 446–451
Liu, Li-Kang — (see Jeng, Tzer-Ming) **127,** 223–234

Mahalingam, Raghav, and Glezer, Ari — Design and Thermal Characteristics of a Synthetic Jet Ejector Heat Sink. **127,** 172–177
Mai, Y-W — (see Wong, E. H.) **127,** 496–502
Manno, Vincent P. — (see Ting, Ben) **127,** 299–305
Mazotti, William P. — (see Radhakrishnan, Satish) **127,** 391–396
Mościcki, Andrzej, Felba, Jan, Sobierajski, Tadeusz, and Kudzia, Józef — Snap-Curing Electrically Conductive Formulation for Solder Replacement Applications. **127,** 91–95
Mudawar, Issam — (see Qu, Weilin) **127,** 381–390
Mujumdar, Arun Sadashiv — (see Wang, Xiang-Qi) **127,** 357–361(TB)

Nakata, Masashi — (see Fushinobu, Kazuyoshi) **127,** 141–146
Nelson, Dave — (see Zhang, Qian) **127,** 415–429
Neumann, A. — (see Becker, K.-F.) **127,** 1–6
Nguyen, Luu — (see Radhakrishnan, Satish) **127,** 391–396
Nishimura, Hideo — (see Tsukada, Yutaka) **127,** 407–414

Obaid, Ahmad Abu, Sloan, Jay G., Lamontia, Mark A., Paesano, Antonio, Khan, Subhotosh, and Gillespie, John J., Jr. — Experimental In Situ Characterization and Creep Modeling of Tin-Based Solder Joints on Commercial Area Array Packages at −40 °C, 23 °C, and 125 °C. **127,** 430–439
_____, **Sloan, Jay G., Lamontia, Mark A., Paesano, Antonio, Khan, Subhotosh, and Gillespie, John W., Jr.** — Test Method Development to Quantify the In Situ Elastic and Plastic Behavior of 62%Sn–36%Pb–2%Ag Solder Ball Arrays in Commercial Area Array Packages at −40 °C, 23 °C, and 125 °C. **127,** 483–495
Ostmann, A. — (see Becker, K.-F.) **127,** 1–6

Paesano, Antonio — (see Obaid, Ahmad Abu) **127,** 430–439
_____ (see Obaid, Ahmad Abu) **127,** 483–495
Paik, Kyung-Wook — (see Kwon, Woon-Seong) **127,** 86–90
Pallavicini, Hector — (see Zhang, Qian) **127,** 415–429
Pang, Ying Feng, Scott, Elaine P., Chen, Jonah Zhou, and Thole, Karen A. — Thermal Design and Optimization Methodology for Integrated Power Electronics Modules. **127,** 59–66
Panton, Ronald L. — (see Wang, Daijiao) **127,** 120–126
_____ (see Wang, Daijiao) **127,** 440–445
Park, Jong-Jin, and Taya, Minoru — Design of Micro-Temperature Sensor Array With Thin Film Thermocouples. **127,** 286–289
Park, Tae-Sang, and Lee, Soon-Bok — Low Cycle Fatigue Testing of Ball Grid Array Solder Joints under Mixed-Mode Loading Conditions. **127,** 237–244
Pei, Bau-Shi — (see Wang, S. Kong) **127,** 523–529
Pei, Chien-Chang, and Hwang, Sheng-Jye — Three-Dimensional Paddle Shift Modeling for IC Packaging. **127,** 324–334
_____, **and Hwang, Sheng-Jye** — Prediction of Wire Sweep During the Encapsulation of IC Packaging With Wire Density Effect. **127,** 335–339
Pei, Z. J. — (see Sun, X. K.) **127,** 189–192(TB)
Pham-Van-Diep, Gerald — (see Aravamudhan, Srinivasa) **127,** 340–352
Pickering, Jason P. — (see Chen, B. L.) **127,** 466–473
Polyakov, A., Bartek, M., and Burghartz, J. N. — Area-Selective Adhesive Bonding Using Photosensitive BCB for WL CSP Applications. **127,** 7–11
Prabhakumar, Ananth — (see Rubinsztajn, Slawomir) **127,** 77–85

Qu, Weilin, and Mudawar, Issam — A Systematic Methodology for Optimal Design of Two-Phase Micro-Channel Heat Sinks. **127,** 381–390

Radhakrishnan, Satish, Subbarayan, Ganesh, Nguyen, Luu, and Mazotti, William P. — A Systems Approach for Analyzing Uncertainties in Misalignment of a Fiberoptic System. **127,** 391–396
Rafanelli, Anthony J., Reviewer — Environment-Friendly Electronics: Lead-Free Technology. **127,** 537–538(BR)
_____ Practical Guide to the Packaging of Electronics. **127,** 539(BR)
Rambo, Jeffrey, and Joshi, Yogendra — Thermal Performance Metrics for Arranging Forced Air Cooled Servers in a Data Processing Cabinet. **127,** 452–459
Ramone, Y. — (see den Toonder, J. M. J.) **127,** 276–285
Reichl, H. — (see Becker, K.-F.) **127,** 1–6
Rodgers, Peter, Eveloy, Valérie, and Hashmi, M. S. J. — An Investigation Into the Potential of Low-Reynolds Number Eddy Viscosity Turbulent Flow Models to Predict Electronic Component Operational Temperature. **127,** 67–75
_____ (see Eveloy, Valérie) **127,** 245–254
Rubinsztajn, Slawomir, Buckley, Donald, Campbell, John, Esler, David, Fiveland, Eric, Prabhakumar, Ananth, Sherman, Donna, and Tonapi, Sandeep — Development of Novel Filler Technology for No-Flow and Wafer Level Underfill Materials. **127,** 77–85

Saddoughi, Seyed — (see Garg, Jivtesh) **127,** 503–511
Sakane, Masao — (see Tsukada, Yutaka) **127,** 407–414
Santos, Daryl — (see Aravamudhan, Srinivasa) **127,** 340–352
Scott, Elaine P. — (see Pang, Ying Feng) **127,** 59–66
Seah, S. K. W. — (see Wong, E. H.) **127,** 496–502
Sham, Man-Lung, and Kim, Jang-Kyo — Experiment and Numerical Analysis of the Residual Stresses in Underfill Resins for Flip Chip Package Applications. **127,** 47–51
Sharif, A. — (see Islam, M. N.) **127,** 365–369
Sherman, Donna — (see Rubinsztajn, Slawomir) **127,** 77–85
Shi, X. Q. — (see Chen, B. L.) **127,** 466–473
Sloan, Jay G. — (see Obaid, Ahmad Abu) **127,** 430–439
_____ (see Obaid, Ahmad Abu) **127,** 483–495
Sobierajski, Tadeusz — (see Mościcki, Andrzej) **127,** 91–95
Spelt, J. K. — (see Ghorbani, H. R.) **127,** 314–323
Subbarayan, Ganesh — (see Radhakrishnan, Satish) **127,** 391–396
Sun, X. K., Xin, X. J., and Pei, Z. J. — Finite Element Analysis of Die-Strength Testing Configurations for Thin Wafers. **127,** 189–192(TB)
Suwa, Tohru — (see Hadim, Hamid) **127,** 306–313

Tan, S. C. — (see Lee, K. K.) **127,** 52–58
Tang, H. — (see Basaran, C.) **127,** 208–214
Tay, Andrew A. O. — Modeling of Interfacial Delamination in Plastic IC Packages Under Hygrothermal Loading. **127,** 268–275
Taya, Minoru — (see Park, Jong-Jin) **127,** 286–289
Teneketges, N. — (see Cepeda-Rizo, J.) **127,** 178–184
Thole, Karen A. — (see Pang, Ying Feng) **127,** 59–66
Ting, Ben, and Manno, Vincent P. — Transient Thermomechanical Simulation of Laser Hammering in Optoelectronic Package Manufacturing. **127,** 299–305
Tonapi, Sandeep — (see Rubinsztajn, Slawomir) **127,** 77–85
Tou, K. W. — (see Bhowmik, H.) **127,** 193–199
_____ (see Bhowmik, H.) **127,** 215–222
Tso, C. P. — (see Bhowmik, H.) **127,** 215–222
Tsukada, Yutaka, Nishimura, Hideo, Yamamoto, Hiroki, and Sakane, Masao — A Strain Rate Ratio Approach for Assessing Creep-Fatigue Life of 63Sn-37Pb Solder Under Shear Loading. **127,** 407–414

van Dijken, A. R. — (see den Toonder, J. M. J.) **127,** 276–285

Wang, Daijiao, and Panton, Ronald L. — Experimental Study of Void Formation in High-Lead Solder Joints of Flip-Chip Assemblies. **127,** 120–126
_____, **and Panton, Ronald L.** — Effect of Reversing Heat Flux Direction During Reflow on Void Formation in High-Lead Solder Bumps. **127,** 440–445
Wang, Meng-Ping — (see Wu, Ming-Chang) **127,** 474–482
Wang, S. Kong, Hung, Tzu-Chen, Pei, Bau-Shi, Chen, An-Fong, and Du, Ja-Lin — A Numerical Study of the Enhancement of Chip Cooling via a Flow-Disturbing Obstruction Block. **127,** 523–529
Wang, Tong Hong, and Lai, Yi-Shao — Submodeling Analysis for Path-Dependent Thermomechanical Problems. **127,** 135–140
Wang, Xiang-Qi, Yap, Christopher, and Mujumdar, Arun Sadashiv — Effects of Two-Dimensional Roughness in Flow in Microchannels. **127,** 357–361(TB)
Weaver, Stanton — (see Garg, Jivtesh) **127,** 503–511
Wen, Sihai, and Chung, D. D. L. — Effect of Stress on the Dielectric Constant of Alumina. **127,** 235–236
Wetzel, Todd — (see Garg, Jivtesh) **127,** 503–511

Wirtz, Richard A. — (see Xu, Jun) **127,** 353–356(TB)
Wong, E. H. — Dynamics of Board-Level Drop Impact. **127,** 200–207
_____, **Mai, Y-W, and Seah, S. K. W.** — Board Level Drop Impact—Fundamental and Parametric Analysis. **127,** 496–502
Wu, Jenq-Dah — (see Jen, Ming-Hwa R.) **127,** 446–451
Wu, Ming-Chang, Wu, Tiao-Yuan, Kuo, Sheng-Tzung, Wang, Meng-Ping, and Hung, Ying-Huei — Thermal Performance Investigation for Confined Heat Sinks By Using a Modified Transient Liquid Crystal Technique. **127,** 474–482
Wu, Tiao-Yuan — (see Wu, Ming-Chang) **127,** 474–482

Xin, X. J. — (see Sun, X. K.) **127,** 189–192(TB)
Xu, Jun, and Wirtz, Richard A. — In-Plane Effective Thermal Conductivity of Symmetric, Diamond-Weave Screen Laminates. **127,** 353–356(TB)

Yamamoto, Hiroki — (see Tsukada, Yutaka) **127,** 407–414
Yang, Ji Hyuck, and Lee, Kang Yong — Hygrothermal Cracking Analysis of Plastic IC Package. **127,** 164–171
Yap, Christopher — (see Wang, Xiang-Qi) **127,** 357–361(TB)
Yasuda, Kiyokazu, Kim, Jong-Min, and Fujimoto, Kozo — Adhesive Joining Process and Joint Property With Low Melting Point Filler. **127,** 12–17
_____ (see Kim, Jong-Min) **127,** 18–24
Ye, H. — (see Basaran, C.) **127,** 157–163
Yeh, Hsien-Yang — (see Cepeda-Rizo, J.) **127,** 178–184
_____ (see Cepeda-Rizo, J.) **127,** 185–188
Yim, Myung-Jin — (see Kwon, Woon-Seong) **127,** 86–90
Yu, Xiaomei, Li, Ting, Hao, Lin, and Zhang, Dacheng — PCR Microchip Array Based on Polymer Bonding Technique. **127,** 38–42

Zhai, Linda — (see Chen, Xu) **127,** 460–465
Zhang, Dacheng — (see Yu, Xiaomei) **127,** 38–42
Zhang, G. Q. — (see den Toonder, J. M. J.) **127,** 276–285
_____ (see Fan, X. J.) **127,** 262–267
_____ (see Gonda, V.) **127,** 33–37
_____ (see Jansen, K. M. B.) **127,** 530–536
Zhang, Qian, Dasgupta, Abhijit, and Haswell, Peter — Isothermal Mechanical Durability of Three Selected PB-Free Solders: Sn3.9Ag0.6Cu, Sn3.5Ag, and Sn0.7Cu. **127,** 512–522
_____, **Dasgupta, Abhijit, Nelson, Dave, and Pallavicini, Hector** — Systematic Study on Thermo-Mechanical Durability of Pb-Free Assemblies: Experiments and FE Analysis. **127,** 415–429
Zhao, Shufeng — (see Chen, Xu) **127,** 460–465
Zhao, Y. — (see Basaran, C.) **127,** 208–214
Zhong, Z. W. — Various Adhesives for Flip Chips. **127,** 29–32
_____, **Lim, S. C., and Asundi, A.** — Optical Fiber Shifts and Shear Stains in V-Groove Arrays for Optical MEMS Packaging. **127,** 25–28
Zhou, J. — (see Fan, X. J.) **127,** 262–267